

L Number	Hits	Search Text	DB	Time stamp
1	5284	324/72.5,158.1,601,130,202,765.ccls.	USPAT	2003/10/17 10:51
2	159	361/771.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 10:51
3	1612	174/261.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 10:51
4	332	calibrat\$4 near5 test\$4 near5 (wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 10:54
5	34	324/72.5,158.1,601,130,202,765.ccls. and (calibrat\$4 near5 test\$4 near5 (wafer or substrate) )	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 10:53
6	0	361/771.ccls. and (calibrat\$4 near5 test\$4 near5 (wafer or substrate) )	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 10:53
7	0	174/261.ccls. and (calibrat\$4 near5 test\$4 near5 (wafer or substrate) )	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 10:53
8	2784	calibrat\$4 near5 (wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 10:54
9	69	324/72.5,158.1,601,130,202,765.ccls. and (calibrat\$4 near5 (wafer or substrate) )	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 10:54
10	0	361/771.ccls. and (calibrat\$4 near5 (wafer or substrate) )	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 10:54
11	1	174/261.ccls. and (calibrat\$4 near5 (wafer or substrate) )	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 10:57
12	0	U5-6,476,630 U5-5,485,080 U5-6.326,801 U5-6,239,5906,420,892	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 10:57
13	0	U5-6,476,630 U5-5,485,080 U5-6.326,801 U5-6,239,590	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 10:57
14	10	(( "6,420,892" ) or ( "6,476,630" ) or ( "5,485,080" ) or ( "6,326,801" ) or ( "6,239,590" ) ).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 10:58
15	4	("5053700"   "5389556"   "5399505"   "6037794").PN.	USPAT	2003/10/17 10:59

16	15	("4918374"   "5004340"   "5060371"   "5483741"   "5508629"   "5599464"   "5640101"   "5656943"   "5686317"   "5869974"   "5894161"   "5915755"   "6048750"   "6060891"   "6072321").PN.	USPAT	2003/10/17 10:59
17	34	("4918374"   "5004340"   "5060371"   "5150041"   "5483741"   "5508629"   "5539676"   "5599464"   "5633122"   "5640101"   "5642056"   "5656943"   "5678301"   "5686317"   "5861759"   "5869974"   "5894161"   "5915755"   "5952840"   "6048750"   "6060891"   "6072321"   "6078186"   "6107109"   "6130148"   "6181144"   "6211960"   "6218848"   "6239590"   "6246250"   "6261854"   "6275052"   "6294837"   "6300786").PN.	USPAT	2003/10/17 11:01
18	3	786667.URPN.	USPAT	2003/10/17 11:02
-	246	calibrat\$4 near5 test\$4 near5 (wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 10:52
-	219837	contact and conductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/06 16:45
-	54	(calibrat\$4 near5 test\$4 near5 (wafer or substrate)) and (contact and conductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/06 16:46
-	10	(calibrat\$4 near5 test\$4 near5 (wafer or substrate)) and 324/72.5, 601,130,202.ccls.	USPAT	2002/11/06 17:21
-	2	"6300757"	USPAT	2002/11/06 17:21
-	7	("5734268"   "5748506"   "5866437"   "5884236"   "5910011"   "5929628"   "6032107").PN.	USPAT	2002/11/06 17:36
-	1	6300757.URPN.	USPAT	2002/11/06 17:37
-	776	calibrat\$4 same (contact same pair)	USPAT	2002/11/06 18:14
-	162	(calibrat\$4 same (contact same pair)) and (wafer or substrate or semiconductor)	USPAT	2002/11/06 17:50
-	6540	calibrat\$4 same (wafer or substrate or semiconductor)	USPAT	2002/11/06 18:14
-	230	(calibrat\$4 same (wafer or substrate or semiconductor)) and (contact with pair)	USPAT	2002/11/06 18:17
-	56	(calibrat\$4 same (wafer or substrate or semiconductor)) and ((contact with pair) with (semiconductor or wafer or substrate))	USPAT	2002/11/06 18:28
-	71	(calibrat\$4 same (wafer or substrate or semiconductor)) and (((contact or pad) with pair) with (semiconductor or wafer or substrate))	USPAT	2002/11/06 18:28
-	3603	calibrat\$4 with probe	USPAT	2002/11/07 13:12
-	652	(calibrat\$4 with probe ) with system	USPAT	2002/11/07 13:13
-	96	((calibrat\$4 with probe ) with system) and wafer	USPAT	2002/11/07 13:13
-	16876	"96" and (refer\$6 near3 point)	USPAT	2002/11/07 13:52
-	27	((calibrat\$4 with probe ) with system) and wafer) and (refer\$6 near3 point)	USPAT	2002/11/07 14:43
-	1744	calibrat\$4 near5 contact	USPAT	2002/11/07 14:52

-	264	(calibrat\$4 near5 contact ) and (wafer or semiconductor)	USPAT	2002/11/07 14:52
-	106	((calibrat\$4 near5 contact ) and (wafer or semiconductor)) and probe	USPAT	2002/11/07 14:53
-	8	"5162728"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/16 17:57
-	4	((("4746861") or ("4780086"))).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/16 17:57
-	2	("5866998").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/17 10:48
-	0	316/771.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/17 11:54
-	153	361/771.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/17 11:54
-	1521	174/261.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/17 11:59
-	292	calibrat\$4 near5 test\$4 near5 (wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/17 11:56
-	0	contact with lenght with trace	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/17 11:56
-	267	contact with length with trace	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/17 11:57
-	17	contact with equal with length with trace	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/17 11:58
-	1	(contact with equal with length with trace) and 324/750-765,158.1.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/17 11:58
-	0	(contact with equal with length with trace) and 316/771.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/17 11:59
-	0	(contact with equal with length with trace) and 361/771.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/17 11:59

-	1	(contact with equal with length with trace) and 174/261.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/17 15:51
-	633	324/755.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/17 15:51